

Title (en)

Multilayer printed wiring board and process for manufacturing the same.

Title (de)

Mehrschichtige, gedruckte Leiterplatte und Verfahren zu ihrer Herstellung.

Title (fr)

Circuit imprimé multicouche et son procédé de fabrication.

Publication

EP 0481472 A1 19920422 (EN)

Application

EP 91117690 A 19911016

Priority

JP 27811090 A 19901017

Abstract (en)

The multilayer printed wiring board of this invention consists of a base substrate (11), a plurality of multilayer interconnections (12a to 12c) formed by lamination of metal wiring layer and insulation layer on the base substrate and ceramic substrates (13a, 13b) provided with through holes for electrical connection of the multilayer interconnections and inserted between two multilayer interconnections. The manufacturing method comprises lamination of metal wiring layers and insulation layers on both sides of ceramic substrates to form multilayer interconnections, forming of a multilayer interconnection on the base substrate (11) by laminating a wiring layer and an insulation layer, and integration of the ceramic substrates (13a, 13b) with metal wiring layers and the base substrate (11) placed together under heated and pressurized conditions. <IMAGE>

IPC 1-7

H05K 3/46

IPC 8 full level

H01L 21/48 (2006.01); **H05K 3/46** (2006.01); **H05K 1/03** (2006.01); **H05K 3/28** (2006.01)

CPC (source: EP US)

H01L 21/4857 (2013.01 - EP US); **H05K 3/4614** (2013.01 - EP US); **H05K 3/4629** (2013.01 - EP US); **H01L 2924/15312** (2013.01 - EP US); **H01L 2924/3011** (2013.01 - EP US); **H05K 1/0306** (2013.01 - EP US); **H05K 3/28** (2013.01 - EP US); **H05K 3/4605** (2013.01 - EP US); **H05K 3/4623** (2013.01 - EP US); **H05K 3/4644** (2013.01 - EP US); **H05K 3/4647** (2013.01 - EP US); **H05K 2201/0154** (2013.01 - EP US); **H05K 2203/1189** (2013.01 - EP US); **H05K 2203/1572** (2013.01 - EP US); **Y10T 29/49126** (2015.01 - EP US); **Y10T 29/49165** (2015.01 - EP US)

Citation (search report)

- [A] EP 0357088 A2 19900307 - NEC CORP [JP]
- [A] DE 3639402 A1 19880519 - SIEMENS AG [DE]
- [A] EP 0260857 A2 19880323 - NEC CORP [JP]

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EP0526107A1; US5628852A; US5686702A

Designated contracting state (EPC)

DE FR GB NL

DOCDB simple family (publication)

EP 0481472 A1 19920422; **EP 0481472 B1 19960612**; CA 2053448 A1 19920418; CA 2053448 C 19960917; DE 69120198 D1 19960718; DE 69120198 T2 19961010; JP 2551224 B2 19961106; JP H04152693 A 19920526; US 5337466 A 19940816; US 5382757 A 19950117

DOCDB simple family (application)

EP 91117690 A 19911016; CA 2053448 A 19911015; DE 69120198 T 19911016; JP 27811090 A 19901017; US 172693 A 19930106; US 77824291 A 19911017